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United States Patent [19]

Ishihara

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[54] **IC MODULE**

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[73] Assignee: **Kabushiki Kaisha Toshiba, Kawasaki, Japan**

[**] Term: **14 Years**

[21] Appl. No.: **62,839**

[22] Filed: **Nov. 27, 1996**

[30] **Foreign Application Priority Data**

May 29, 1996 [JP] Japan 8-15397

[51] LOC (6) Cl. **14-02**

[52] U.S. Cl. **D14/114; D14/117**

[58] Field of Search D14/114, 117, D14/107; 235/378-380, 487-492; 257/731, 669

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for an IC module, as shown and described.

DESCRIPTION

FIG. 1 is a front, bottom and right side perspective view of an IC module, showing my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a right side elevational view thereof, the opposite side being a mirror image;
FIG. 4 is a top plan view thereof;
FIG. 5 is a bottom plan view thereof; and,
FIG. 6 is a rear elevational view thereof.

1 Claim, 1 Drawing Sheet

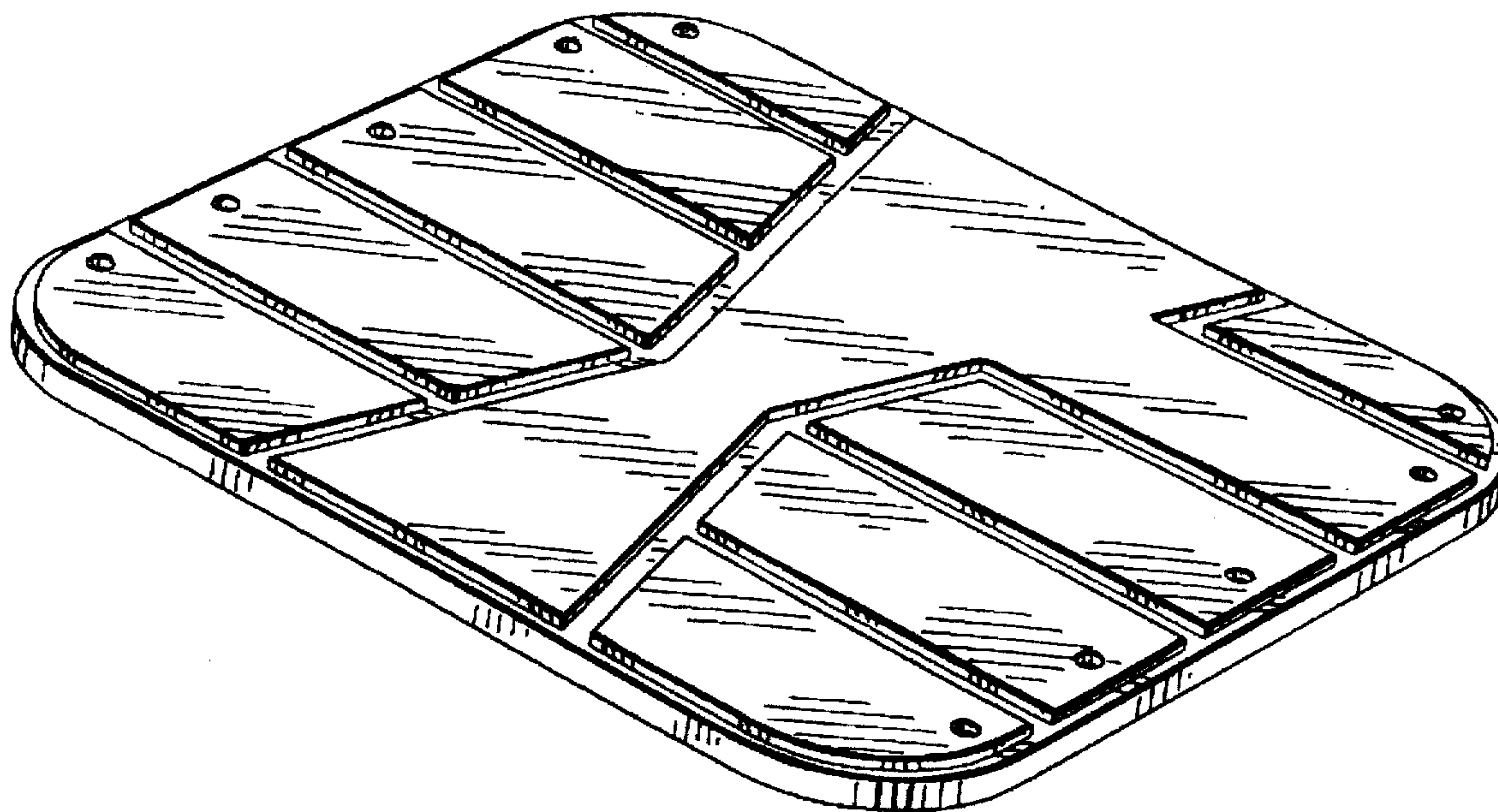


FIG. 4

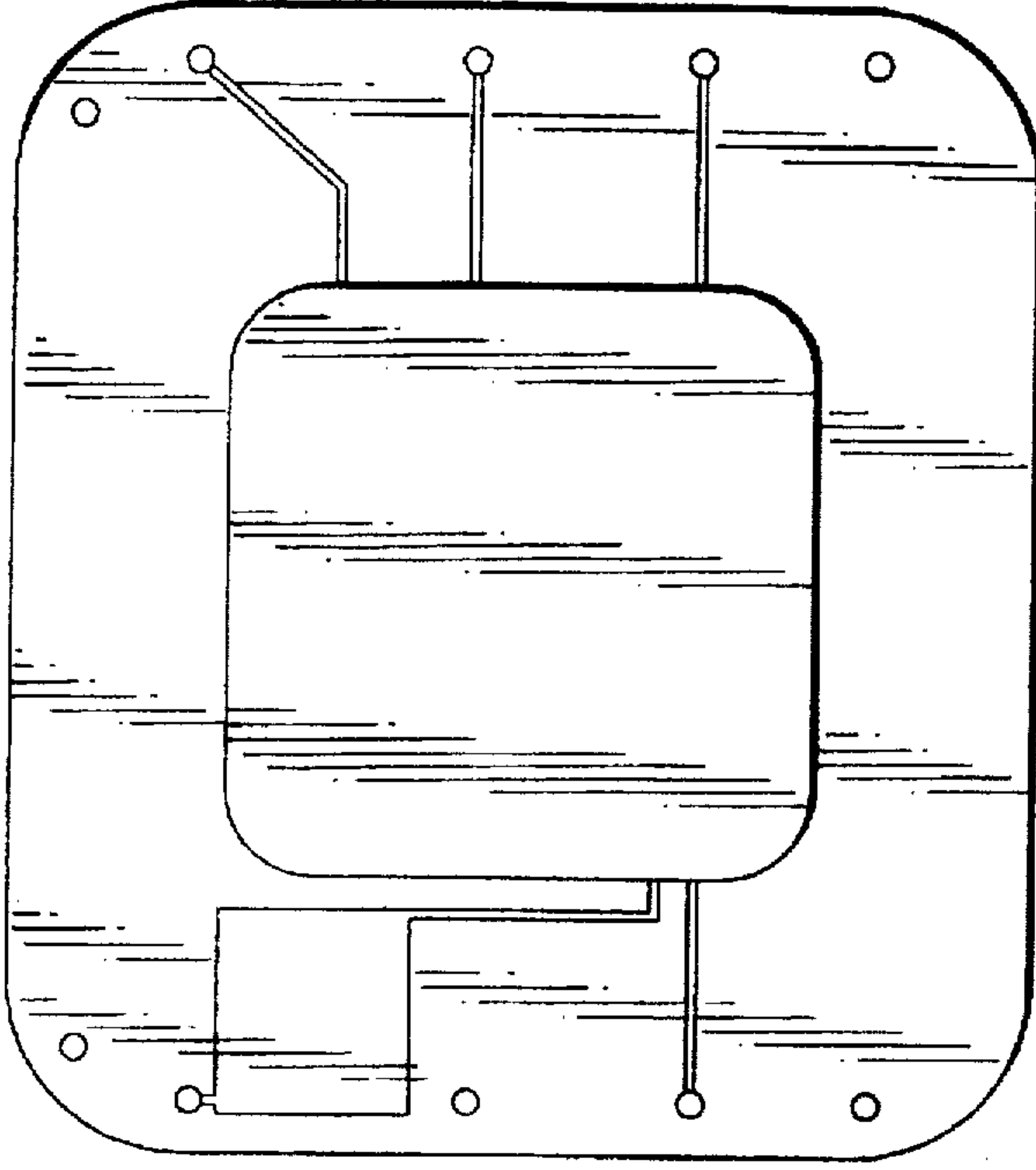


FIG. 5



FIG. 6



FIG. 1

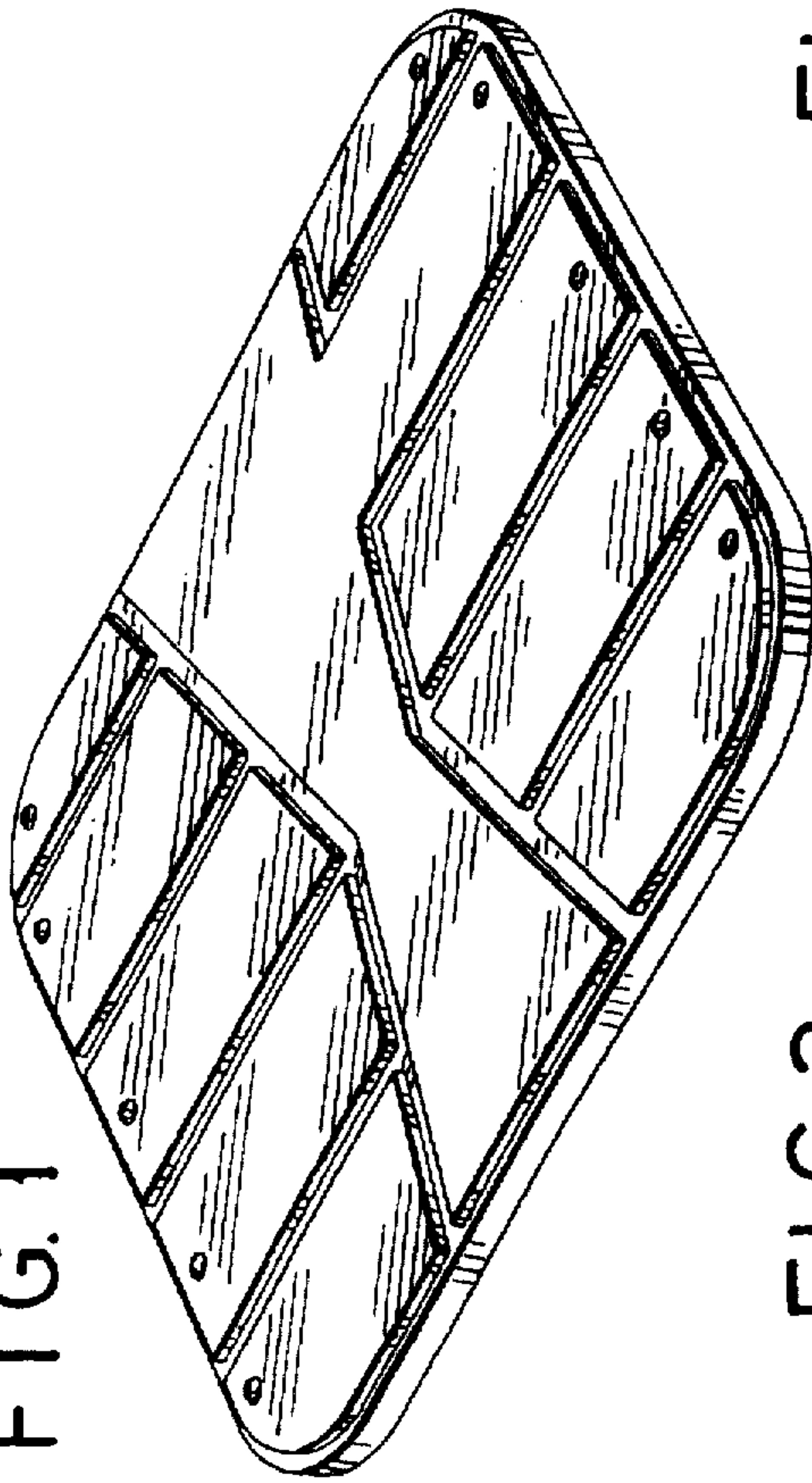


FIG. 2

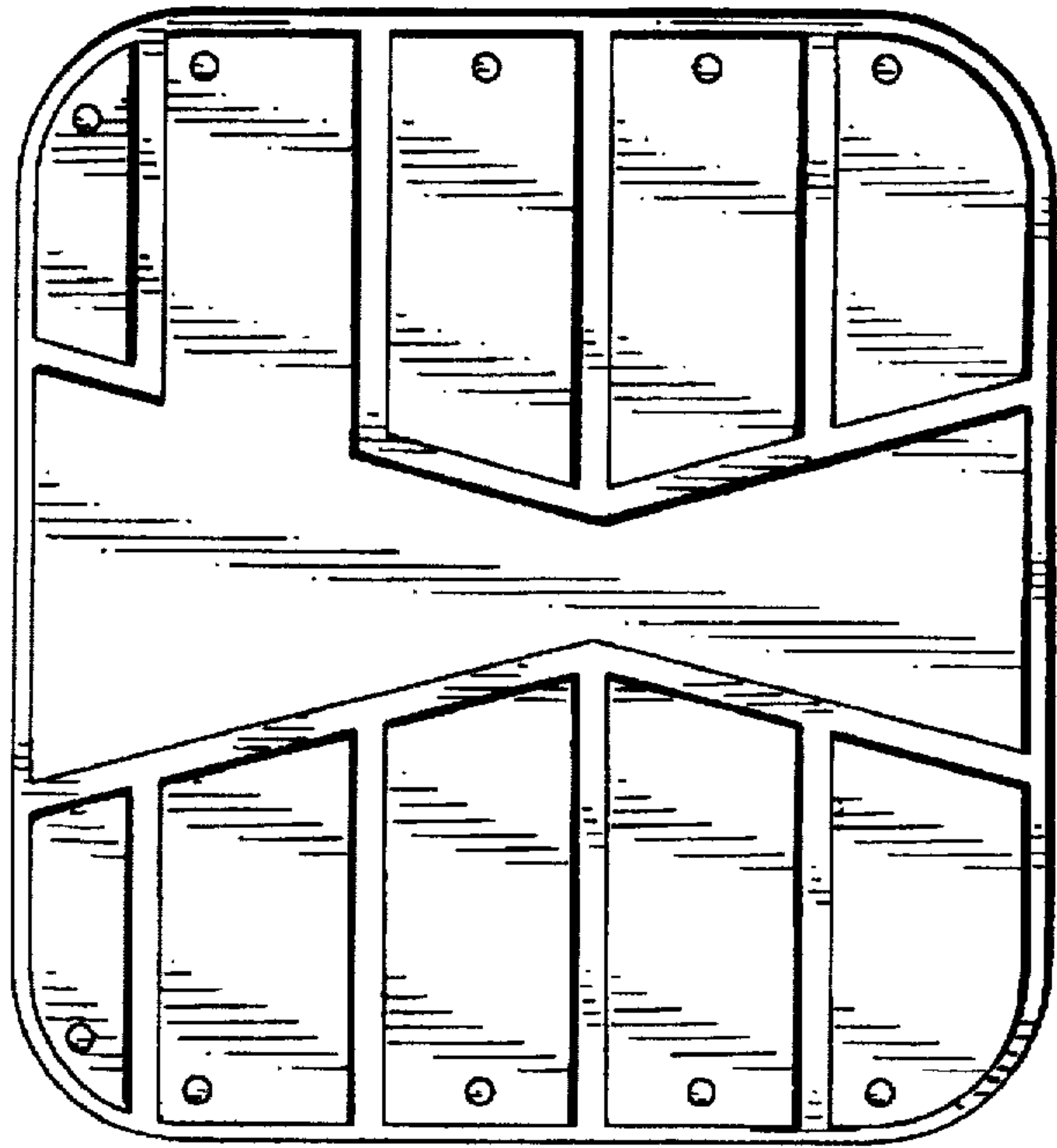


FIG. 3

